

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|-----------------|----------------|--|------------|------------------|-------------------------|-------------------|
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.48657 | 100.0 | 5.2 |
| Subtotal | | | | 0.48657 | 100 | 5.2 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.03752 | 0.1 | 0.401 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.01126 | 0.03 | 0.1203 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.03752 | 0.1 | 0.401 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 37.43538 | 99.77 | 400.0777 |
| Subtotal | | | | 37.52168 | 100 | 401 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 2.84304 | 4.8 | 30.384 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 5.923 | 10.0 | 63.3 |
| | Filler | Silica fused | 60676-86-0 | 50.34549 | 85.0 | 538.05 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.11846 | 0.2 | 1.266 |
| Subtotal | | | | 59.22999 | 100 | 633 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 2.33926 | 100.0 | 25 |
| Subtotal | | | | 2.33926 | 100 | 25 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.03572 | 100.0 | 0.3817 |
| | Pure metal | Aluminium (Al) | 7429-90-5 | 0.09673 | 100.0 | 1.03378 |
| Subtotal | | | | 0.13245 | 200 | 1.41548 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.0058 | 2.0 | 0.062 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.00725 | 2.5 | 0.0775 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.27701 | 95.5 | 2.9605 |
| Subtotal | | | | 0.29006 | 100 | 3.1 |
| Total | | | | 100.00001 | 100 | 1068.71548 |

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